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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Vishnu K. Agarwal et al.

Application No.: 09/590,795

Filed: June 8, 2000

For: METHODS FOR FORMING AND INTEGRATED
CIRCUIT STRUCTURES CONTAINING
RUTHENIUM AND TUNGSTEN CONTAINING
LAYERS

Examiner:

Date: September 8, 2000

Art Unit:

CERTIFICATE OF MAILING

I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service on September 8, 2000 as First Class Mail in an envelope addressed to: COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231.



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INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. § 1.97(b)(1)

TO THE COMMISSIONER FOR PATENTS
Washington, DC 20231

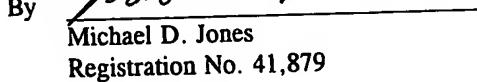
Sir:

Listed on the accompanying form PTO-1449 and enclosed herewith are several English-language documents. Applicants respectfully request that these documents be listed as references cited on the issued patent. Applicants filed this Information Disclosure Statement within three months of the filing date of a national application. However, if the Patent Office determines that a fee is required for Applicants to file this Information Disclosure Statement, please charge any such fees, or credit overpayment, to Deposit Account No. 02-4550. A duplicate copy of this Information Disclosure Statement is enclosed.

Respectfully submitted,

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